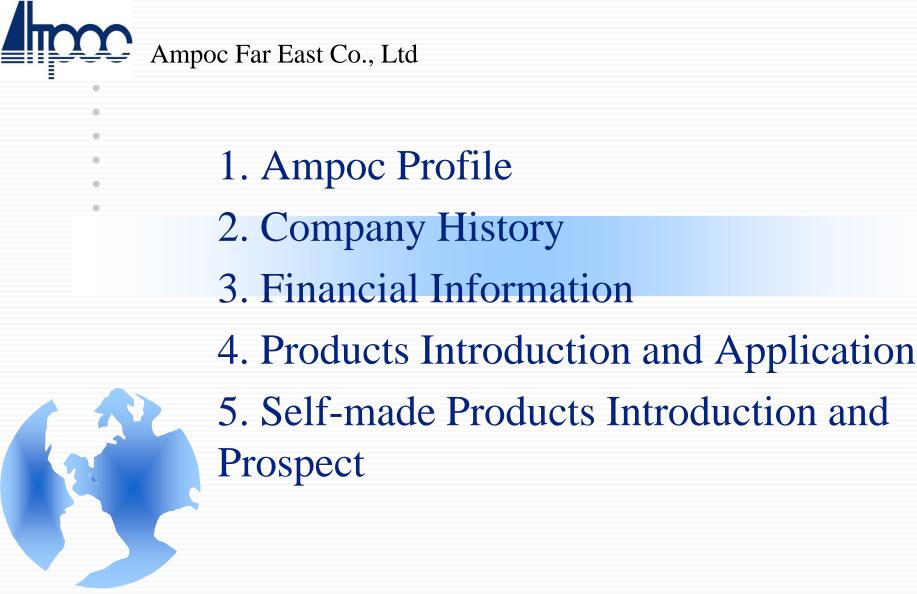




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Investor Conference (Code: 2493)

2022/09/16





1. Company Profile

- **Company : AMPOC Far-East Co., Ltd.**
- Address : 17F., No.171, Sung-Teh Road, Taipei, Taiwan
- Tel: (02) 2726-2220
- Fax: (02) 2726-2227
- E-mail: 1service@ampoc.com.tw

Responsible Person:

Chairman & C.E.O., Mr. Ronald S. Su

Since : November 1, 1980

Paid-up Capital : NT\$ 1,144 Million Employee : 280 people



Chairman & C.E.O., Mr. Ronald S. Su

2000/10

1997/03

1980/11

2. Company History

AMPOC's History



- Ampoc invested in Ampoc Trading (Shanghai) Co., Ltd through the subsidiary in Hong Kong.
 - Ampoc merged Yang Shin Investment Co., Ltd which Ampoc owned 100%.
 - Ampoc was approved to list on the Taiwan Stock Exchange, Stock Code: 2493.
- Stock dividend was issued, resulting in total capital of NT\$905 million.
 - Paid-in capital was increased to NT\$73.7 million.
- Ampoc merged with TTCM and issued additional 21,107,000 shares, paid-in capital increased to NT\$57.1 million.
 - Ampoc was approved as public company.
- 1998/12 Ampoc was engaged in capitalization of NT\$10.2 million, paid-in capital increased to NT\$30 million.
- Ampoc established the inspection lab. with precision instruments to enhance our service quality.
 - Ampoc purchased the office which located at 17F, No.171, Sung-Teh Rd., Sinyi District, Taipei.
- TCM in Japan which was a master manufacturer of PCB Wet Process established TTCM in CHUNG-LI industrial zone, Taiwan. Ampoc invested in TTCM and obtained the sole global distribution agreement except in Japan.
 - Ampoc was founded in Taipei with initially registered capital of NT\$1 million.



3. Financial Information

Condensed Statement of Comprehensive Income from 2020 to 2022 H1

Unit: NT\$ thousands (Except EPS: NT\$)

Year Item	2020 (Consolidate d)	2021 (Consolidated)	2022H1 (Consolidated)
Net Revenue	2,600,664	2,938,974	1,781,039
Gross profit	687,947	778,114	516,013
Gross margin(%)	26.45	26.48	28.97
Operating income	397,524	453,574	370,593
Net income after tax	308,769	343,298	286,374
EPS	2.70	3.00	2.50



Condensed Balance Sheet from 2020 to 2022 H1

Unit: NT\$ thousands (Except EPS: NT\$)

Year Item	2020 (Consolidated)	2021 (Consolidated)	2022H1 (Consolidated)
Current Assets	2,951,161	3,145,641	3,613,578
Non-current Assets	697,883	695,569	655,922
Total Assets	3,649,044	3,841,210	4,269,500
Current Liabilities	1,141,638	1,282,260	1,726,742
Non-current Liabilities	153,401	119,162	126,363
Total Liabilities	1,295,039	1,401,422	1,853,105 6



Financial Analysis from 2020 to 2022 H1

Year Item	2020 (Consolidated)	2021 (Consolidated)	2022H1 (Consolidated)
Debts Ratio (%)	35.49	36.48	43.40
Current Ratio(%)	258.50	245.32	209.27
Average Inventory Turnover (Times)	2.08	1.91	2.14
Return on Equity (%)	13.13	14.32	11.79



4. Products Introduction and Application



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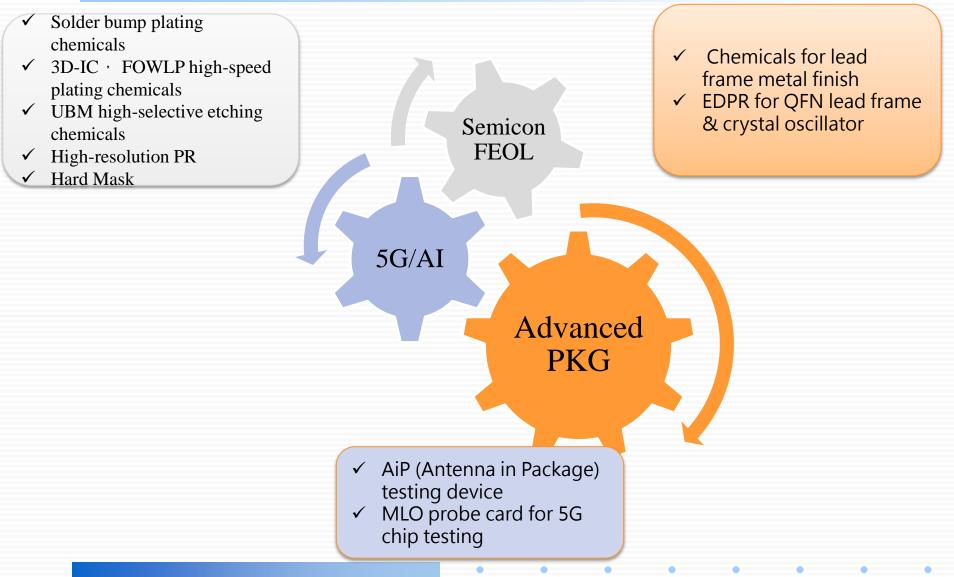
4. Products Introduction and Applications

- Products Introduction
 - AI Arm (AMPOC intelligent arm)系統

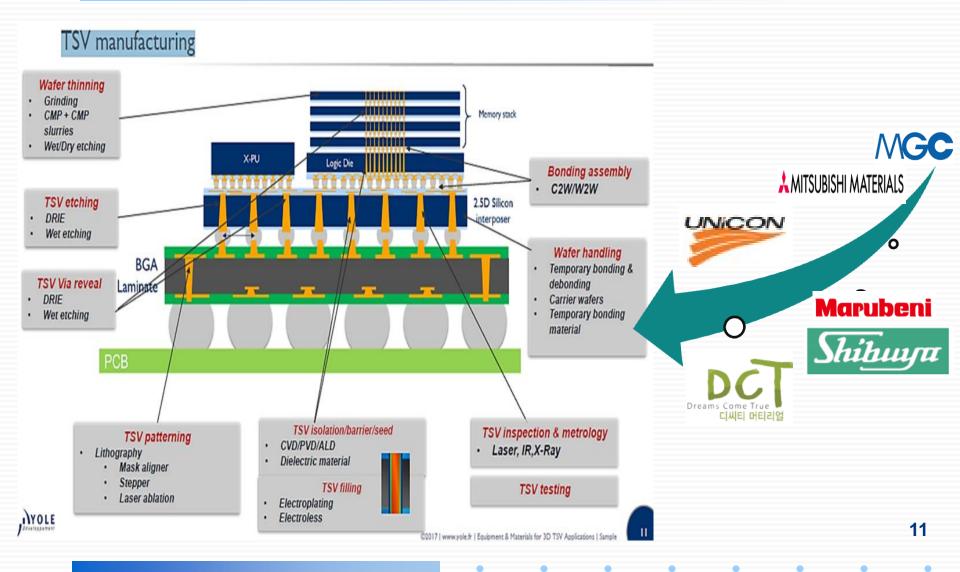
- Laser Heater TC Bonder
- Applications
 - Semiconductor (FEOL)
 - Advanced PKG
 - -5G/AI



Applications-core strategy for development

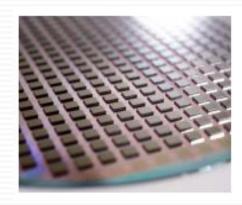


Core technology development





Laser Heater TC Bonder



Fast heating and cooling

Low thermal expansion

Localized heating





Market updates and forecast in 2022

- Unbalanced supply and demand of supply chain
 - To carefully monitor inventory to cope with overbooking phenomenon in 2021-2022;
 - Lockdowns and zero-COVID policy in China made supply chain broken, and caused end market demand recession. Component inventory becomes a serious problem, and further observation on china policy change is necessary.

• Measures

- To fortify the development and expansion regarding advanced process solutions
- To plan strategically on US and China supply chains



5.Self-made Products Introduction and Prospect

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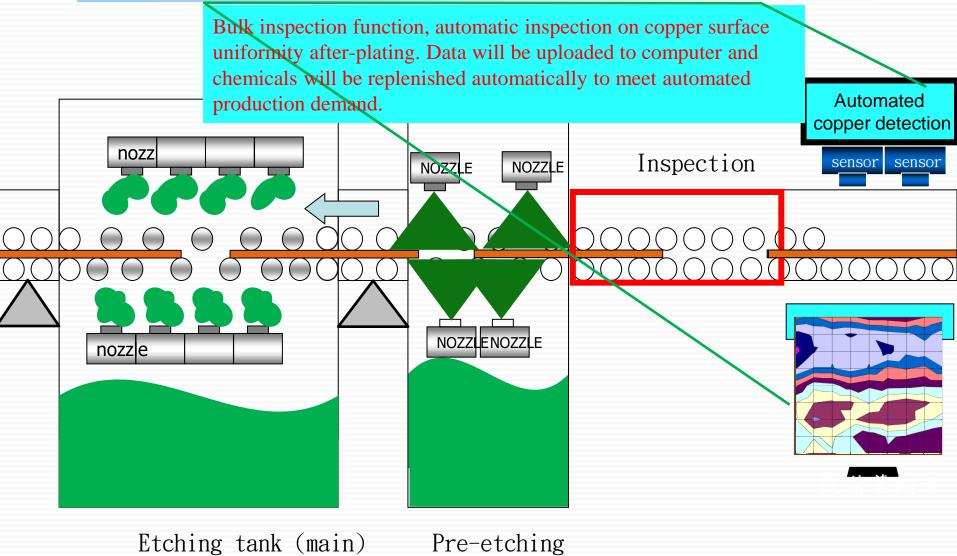


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AI Arm (AMPOC intelligent arm) System



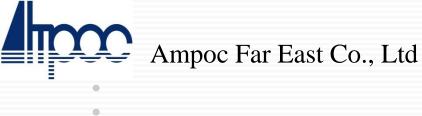
Automated online production system





Taiwan PCB Market review in 2021& outlook in 2023

- The production value of global PCB industry is estimated to reach USD 87B. Top 3 global share ranking: Taiwan 32.8%
 China 31.3%
 & Japan 17.2%.
- 2) Taiwan tops the global market, and China is close behind the ranking. Applications such as 5G, big data, cloud computing, AI, IoT and electric mobile are contributing to the rapid growth of the market.
- 3) The production expansion of PCB can be expected 2023. The products are IC substrate, HDI and FPC for applications such as smart phone, automotive electronics, IoT and network communication.
- 4) Equipment demands outlook :
 - Advanced ABF substrate;
 - High-end products including 5G substrate, SLP, HDI, FPC, etc.;
 - Electric Vehicle & safety devices.



Thank you



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